10-06-2003



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To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof. 2. Name and Address of Receiving Party(ies): 1. Name of Conveying Party(ies): TAKASHI SATOU, SHIGEZUMI MATSUI, PETER Name: Hitachi, Ltd. LEE AND GOUICHI YOKOMIZO Address: 6, Kanda Surugadai 4-chome Additional names of conveying parties attached: Yes No Chiyoda-ku, Tokyo, Japan 9-23-07 Nature of Conveyance: Assignment Merger Security Agreement Change of Name Other: Execution Date: March 26, 2003 (a) Patent Application Number(s): (b) Patent Numbers: If this document is being filed together with a new application, the execution date of the application is: 10/667446 Additional Numbers Attached. 5. Name and Address of Party to whom Correspondence Total Number of Applications and Patents Involved: 1 Concerning this Document Should be Mailed: Name: Stanley P. Fisher Total Fee: \$40.00 (37 C.F.R. § 3.41) Address: Reed Smith LLP 3110 Fairview Park Dr. Ø Enclosed. Suite 1400 Authorized to be charged to deposit account. Falls Church, Va. 22042 Deposit Account Number: 08-1480 ATTACH DUPLICATE COPY OF THIS PAGE IF PAYING BY DEPOSIT ACCOUNT DO NOT USE THIS SPACE Statement and Signature: To the best of my knowledge and belief, the foregoing is true and correct and any attached copy is a true copy of the original document. September 23, 2003 Stanley P. Fisher, Registration No. 24, 344 tuan Carlos A istration No. 34,072 Total number of pages comprising cover sheet:

09/26/2003 CNGUYEN 00000004 10667446

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PATENTS ONLY

RECORDATION FORM COVER SHEET

02 FC:8021

40.00 DP

PATENT REEL: 014544 FRAME: 0770

ASSIGNMENT

(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Hitachi, Ltd., a corporation organized under the laws of Japan, located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi, Ltd.,

its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SEMICONDUCTOR INTEGRATED CIRCUIT AND DATA PROCESSING SUSTEM

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,

to be held and enjoyed by said Hitachi, Ltd.,

its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi, Ltd.,

Signed on the date(s) indicated aside our signatures:

RECORDED: 09/23/2003

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) Takashi Satou Takashi SATOU	26/March / 2003
2) Shigezumi Matsushigezumi MATSUI	26/March /2003
3) AM Peter LEE	26/March/2003
4) Louidie Yokomiya Gouichi YOKOMIZO	26/March / 2003
5)	
6)	
7)	
8)	
9)	
10)	

PATENT REEL: 014544 FRAME: 0771